US0D1033436S

(12) United States Design Patent

Lin et al.

(10) Patent No.: US D1,033,436 S
(45) Date of Patent: ** Jul. 2, 2024

(54) **FAN MODULE COVER**

(71) Applicant: **CHENBRO MICOM CO., LTD.**, New Taipei (TW)

(72) Inventors: **Chiung-Wei Lin**, New Taipei (TW); **Hsin-Lin Teng**, New Taipei (TW)

(73) Assignee: **CHENBRO MICOM CO., LTD.**, New Taipei (TW)

(**) Term: **15 Years**

(21) Appl. No.: **29/797,520**

(22) Filed: **Jul. 1, 2021**

(30) **Foreign Application Priority Data**

Jun. 4, 2021 (TW) 110302945

(51) **LOC (14) Cl.** **14-02**

(52) **U.S. Cl.**
USPC **D14/432**

(58) **Field of Classification Search**
USPC D14/367, 308, 356, 432, 439, 447, 440, D14/366, 313, 251, 224, 238, 217, 260.1, D14/238.1, 224.1; D23/411, 412; D13/155
CPC . G11B 33/0461; G11B 33/027; G11B 33/124; G11B 33/022; G11B 33/142; H05K 7/20172; H05K 7/20145; H05K 7/20154; F01P 2070/50
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D395,816	S	*	7/1998	Colodny	D8/356
6,059,123	A	*	5/2000	Cotutsca	G11B 33/0461 211/41.12
D436,593	S	*	1/2001	Narotzky	D14/432
7,275,646	B2	*	10/2007	Mimlitch, III	H05K 7/186 403/167
D724,354	S	*	3/2015	Sekine	D14/260.1
D734,754	S	*	7/2015	Ficacci	D14/432
D739,358	S	*	9/2015	Collier	D13/155
D742,881	S	*	11/2015	Takano	D14/432
D747,316	S	*	1/2016	Mathews	D14/432
D762,217	S	*	7/2016	Michaud	D14/432
D773,468	S	*	12/2016	Ellis, II	D14/432

(Continued)

FOREIGN PATENT DOCUMENTS

CN	306901273	* 10/2021
JP	D1468071	* 5/2013

OTHER PUBLICATIONS

"Turbo Air M726900100 Pan Duct, Side L" May 31, 2022, Amazon, site visited Apr. 12, 2024: https://www.amazon.ae/Turbo-Air-M726900100-Duct-Side/dp/B076C3SJ6B (Year: 2022).*

(Continued)

Primary Examiner — Jack Reickel
Assistant Examiner — Russell Carnell Smith, Jr.
(74) *Attorney, Agent, or Firm* — CKC & Partners Co., LLC

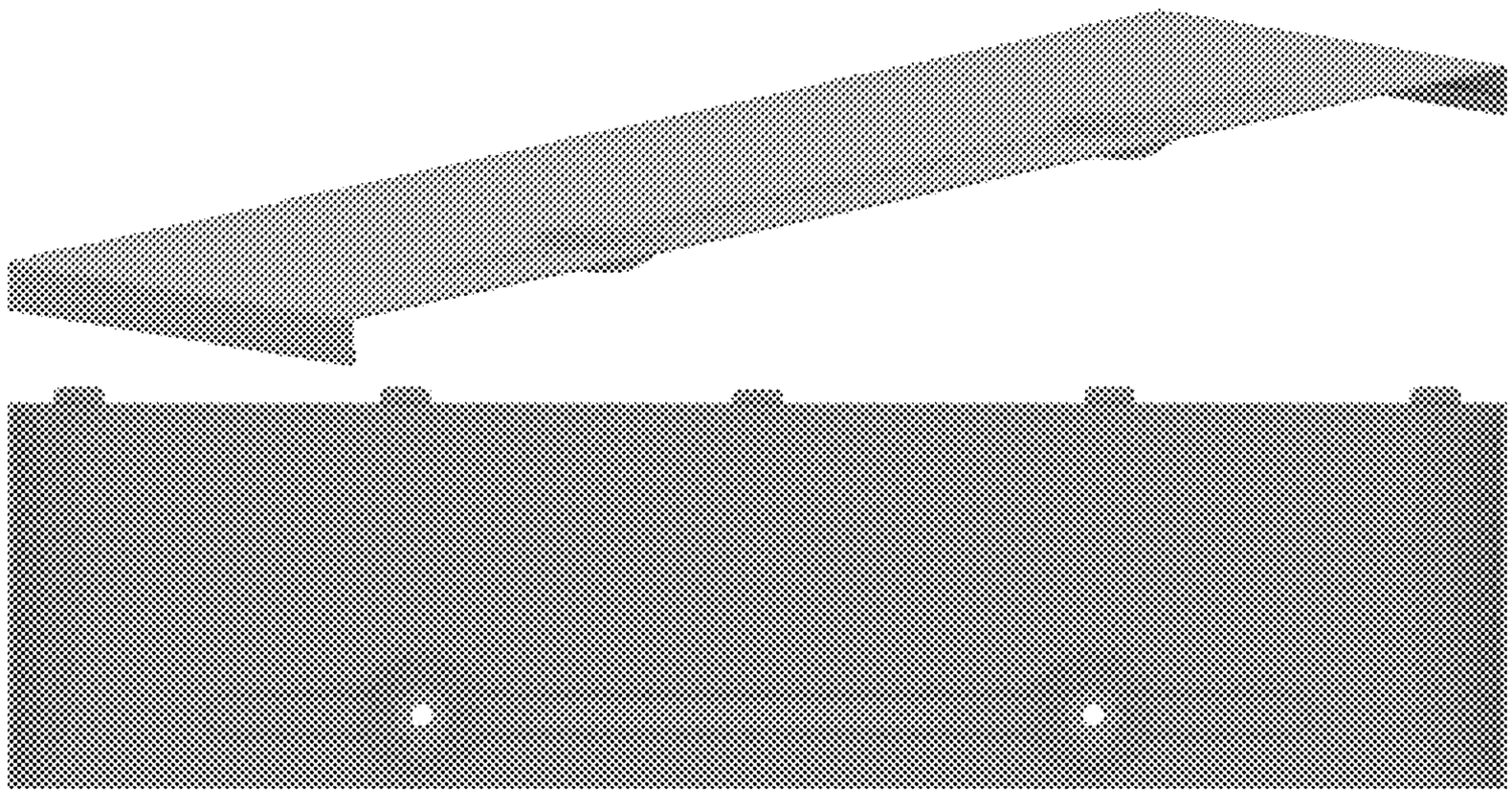
(57) **CLAIM**

The ornamental design for a fan module cover, as shown and described.

DESCRIPTION

FIG. **1** is a front, bottom, left perspective view of a fan module cover, showing the claimed design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a left side elevational view thereof;
FIG. **5** is a right side elevational view thereof;
FIG. **6** is a top plan view thereof; and,
FIG. **7** is a bottom plan view thereof.
Shading is used to illustrate the curvature of the part and not color.

1 Claim, 7 Drawing Sheets



(56) **References Cited**

U.S. PATENT DOCUMENTS

D795,877	S *	8/2017	Barron	D14/432
D803,223	S *	11/2017	LaPree	D14/441
D821,982	S *	7/2018	Fujii	D14/240
10,559,326	B1 *	2/2020	Lin	H05K 7/12
D882,576	S *	4/2020	Crisp	D14/432
D938,920	S *	12/2021	O'Hanlan	D13/152
D989,749	S *	6/2023	Wang	D14/224
2004/0124160	A1 *	7/2004	Vitale	G11B 33/0461 211/40

OTHER PUBLICATIONS

"XYG Study Raspberry Pi Compute Module" Jan. 17, 2017, Amazon, site visited Apr. 12, 2024: https://www.amazon.com/Raspberry-Protection-Computer-XYGStudy-CM4-IO-BOARD-CASE/dp/B08T66KGTL (Year: 2017).*

"Chenbro 84H323610-006 Rear Window with 3-Full Height PCI Slots" Jul. 31, 2013, Amazon, site visited Apr. 12, 2024: https://www.amazon.com/CHENBRO-Accessory-84H323610-006-Window-3-Full/dp/B00HHBISRW (Year: 2013).*

"Chenbro Micom Bracket, Metal Cross-Bar, 2×2.5Inch HDD, RM23612D-4H-L" Aug. 4, 2015, Amazon, site visited Apr. 12, 2024: https://www.amazon.com/CHENBRO-MICOM-USA-INC-RM23612D-4H-L/dp/B017L4QD8A (Year: 2015).*

* cited by examiner

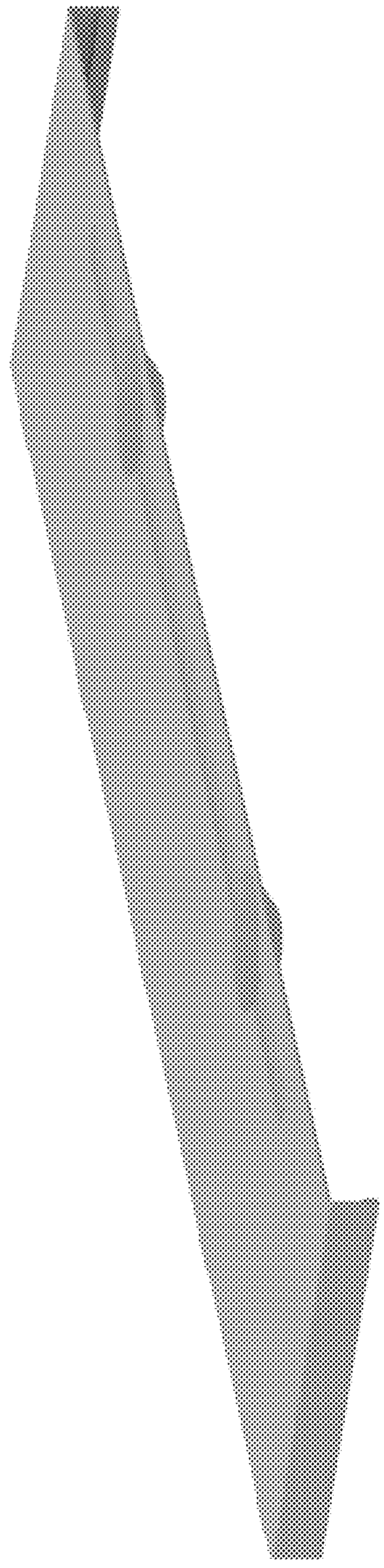


Fig. 1

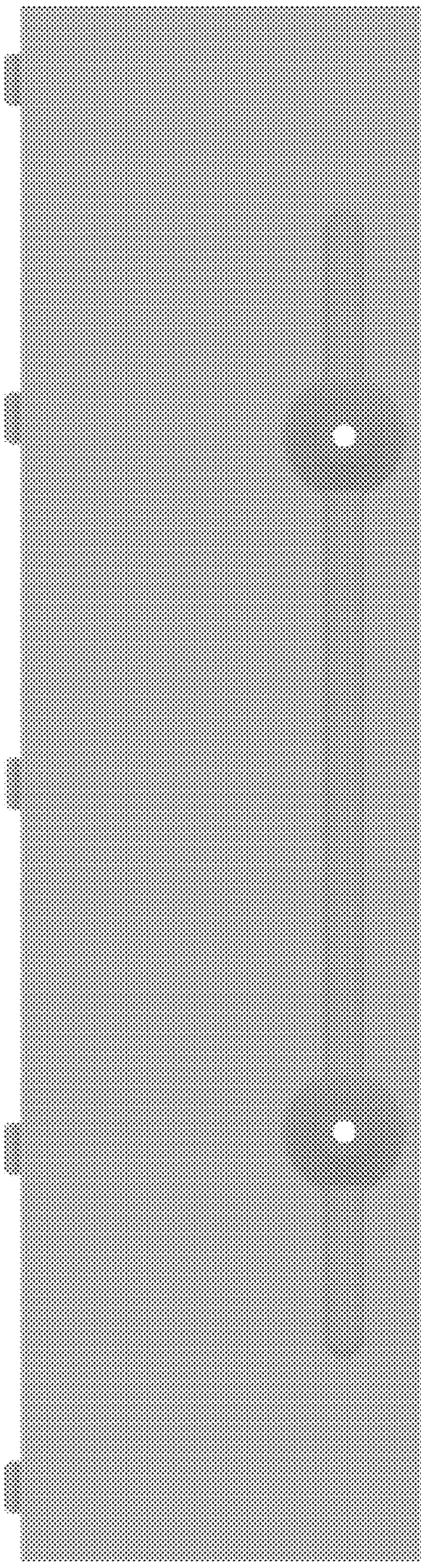


Fig. 2

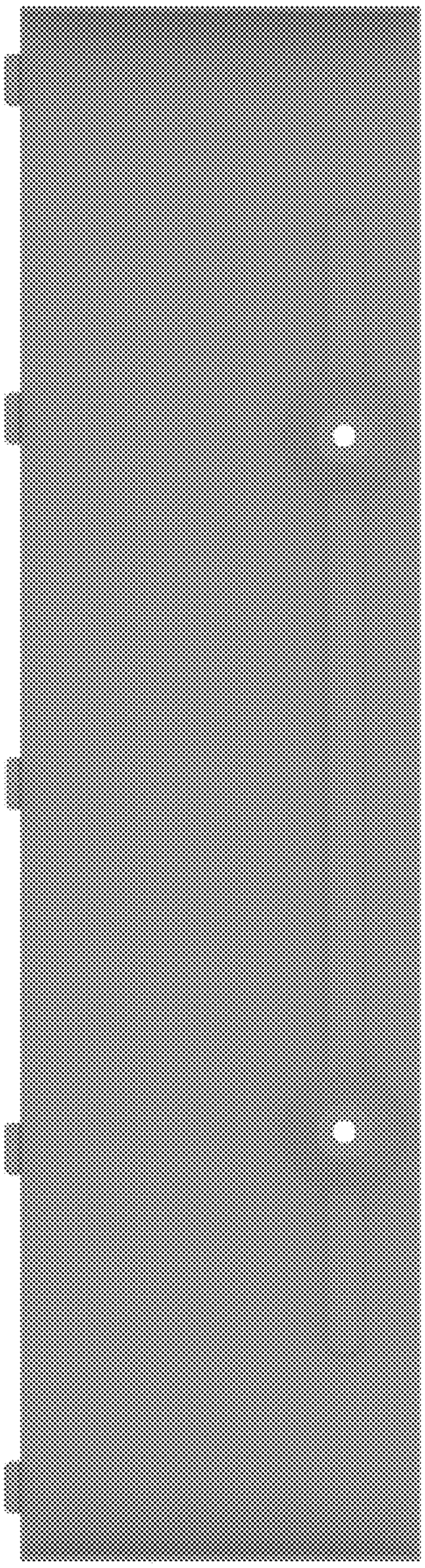


Fig. 3

Fig. 4

Fig. 5

Fig. 6

Fig. 7